

Notice of References Cited	Application/Control No. 09/364,565	Applicant(s)/Patent Under Reexamination WIEDEMANN, RUDOLF A.	
	Examiner John M. Villecco	Art Unit 2612	Page 1 of 1

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.